

## ABSTRACT

A leadframe for use with integrated circuit chips comprising a base metal having a plated layer of nickel  
5 fully covering said base metal; a plated layer of pure tin on said nickel layer, selectively covering areas of said leadframe intended for attachment to other parts; and a plated layer of palladium on said nickel layer, selectively covering areas of said leadframe intended for bonding wire  
10 attachment.

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